AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A method of manipulating semiconductor substrates comprising placing a semiconductor substrate on a transportable electrostatic chuck ~~carrier~~, and keeping the semiconductor substrate clamped ~~placed~~ on the electrostatic chuck ~~carrier~~ for the duration of and between at least two processing steps of the semiconductor substrate without any additional external power supply to recharge the transportable electrostatic chuck during long or several process steps or operation steps.

2. (Currently amended) The method according to claim 1, wherein the transportable electrostatic chuck ~~carrier~~ has a thickness of 0.3 - 2.5 mm, comprising using the electrostatic chuck ~~carrier~~ and the wafer placed thereon in unmodified or little-modified machines for processing semiconductor substrates.

3. (Currently amended) The method according to claim 1,

wherein the transportable electrostatic chuck ~~carrier~~ is a component of an electrostatic chuck ~~carrier~~ system, further comprising inductively charging and discharging without contact the electrostatic chuck ~~carrier~~ system.

4. (Currently amended) The method according to claim 1, wherein the transportable electrostatic chuck ~~carrier~~ includes an integrated electrical charging and/or discharging device, comprising supplying the charging and/or discharging device by a battery or an accumulator.

5. (Currently amended) The method according to claim 4, comprising controlling the transportable electrostatic chuck ~~carrier~~ for electrostatically charging and/or electrostatically discharging by remote control.

6. (Currently amended) The method according to claim 1, comprising electrically charging and/or discharging the transportable electrostatic chuck ~~carrier~~ separately in one or more mobile or stationary transfer stations.

7. (Currently amended) The method according to claim 6, comprising recharging or discharging the electrostatic chuck

~~carrier~~ in a charging station of a processing machine.

8. (Currently amended) The method according to claim 1, comprising monitoring and/or controlling the steps of securing and/or separating the wafer from the electrostatic chuck ~~carrier~~ by means of position sensors.

9. (Currently amended) The method according to claim 1, wherein the transportable electrostatic chuck ~~carrier~~ is used in a unipolar or bipolar electrostatic system.

10. (Currently amended) The method according to claim 1, comprising labeling ~~labelling~~ the electrostatic chuck ~~carrier~~ with an electronic label for facilitating sorting and following a production sequence of individual semiconductor substrates.

11. (Currently amended) An electrostatic carrier system for manipulating semiconductor substrates, the system comprising at least one transportable electrostatic chuck ~~carrier~~ for a semiconductor substrate and at least one transfer station for transferring the transportable electrostatic chuck ~~electroctatic carrier~~ with the semiconductor substrate placed thereon between processing steps.

12. (Currently amended) The system according to claim 11, comprising an integrated electrically charging and/or discharging device for the transportable electrostatic chuck ~~carrier~~, and a battery or an accumulator for supplying the electrical charging and/or discharging device.

13. (Original) The system according to claim 12, comprising a remote control for the charging and/or discharging device.

14. (Original) The system according to claim 11, comprising position sensors for monitoring and/or controlling the position of the semiconductor substrate.

15. (Original) The system according to claim 11, wherein the system is a unipolar or bipolar electrostatic system.

16. (Currently amended) The system according to claim 11, wherein the electrostatic chuck ~~carrier~~ has an electronic label.